# MA3X198 (MA198)

## Silicon epitaxial planar type

#### For wave detection

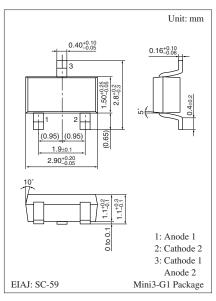
### ■ Features

- Two elements contained in one package, allowing high-density mounting
- Soft recovery characteristic ( $t_{rr} = 100 \text{ ns}$ )

## ■ Absolute Maximum Ratings $T_a = 25$ °C

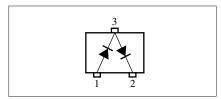
Parameter		Symbol	Rating	Unit
Reverse voltage		$V_R$	40	V
Repetitive peak reverse voltage		$V_{RRM}$	40	V
Forward current	Single	I <sub>F(AV)</sub>	100	mA
(Average)	Series		75	
Repetitive peak	Single	$I_{FRM}$	225	mA
forward current	Series		170	
Non-repetitive peak	Single	$I_{FSM}$	500	mA
forward surge current*	Series		325	
Junction temperature		T <sub>j</sub>	150	°C
Storage temperature		T <sub>stg</sub>	-55 to +150	°C

Note) \*: t = 1 s



Marking Symbol: M2F

### Internal Connection

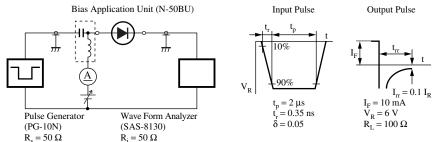


## $\blacksquare$ Electrical Characteristics $\rm\,T_a\,{=}\,25^{\circ}C\pm3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 100 \mu A$	0.65		0.72	V
	$V_{F2}$	$I_R = 100 \text{ mA}$			1.2	V
Reverse current	$I_R$	$V_R = 40 \text{ V}$			10	nA
Terminal capacitance	C <sub>t</sub>	$V_R = 6 \text{ V}, f = 1 \text{ MHz}$		1.0	2.0	pF
Reverse recovery time*	t <sub>rr</sub>	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			100	ns
		$I_{rr} = 0.1 I_R, R_L = 100 \Omega$				

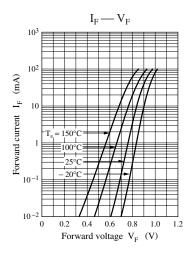
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

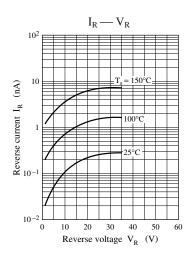
- 2. Absolute frequency of input and output is 10 MHz.
- 3. \*: t<sub>rr</sub> measurement circuit

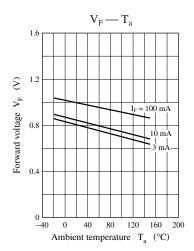


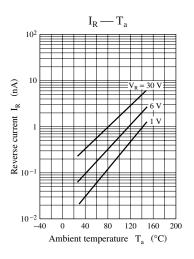
Note) The part number in the parenthesis shows conventional part number.

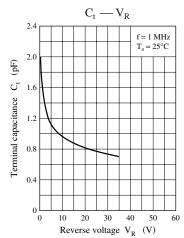
MA3X198 Panasonic

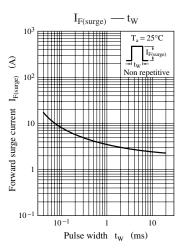












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